

HVU316

Variable Capacitance Diode for BS/CS tuner

REJ03G0108-0400Z

(Previous: ADE-208-035C)

Rev.4.00

Sep.29.2003

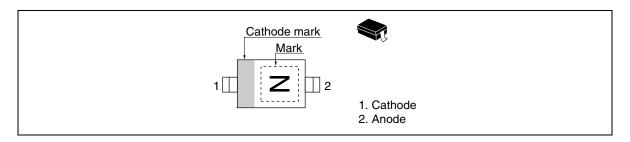
Features

- High capacitance ratio. (n = 9.0 min)
- Low series resistance. (rs = $1.2 \Omega \text{ max}$)
- Ultra small Resin Package (URP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVU316	N	URP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V _R	30	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

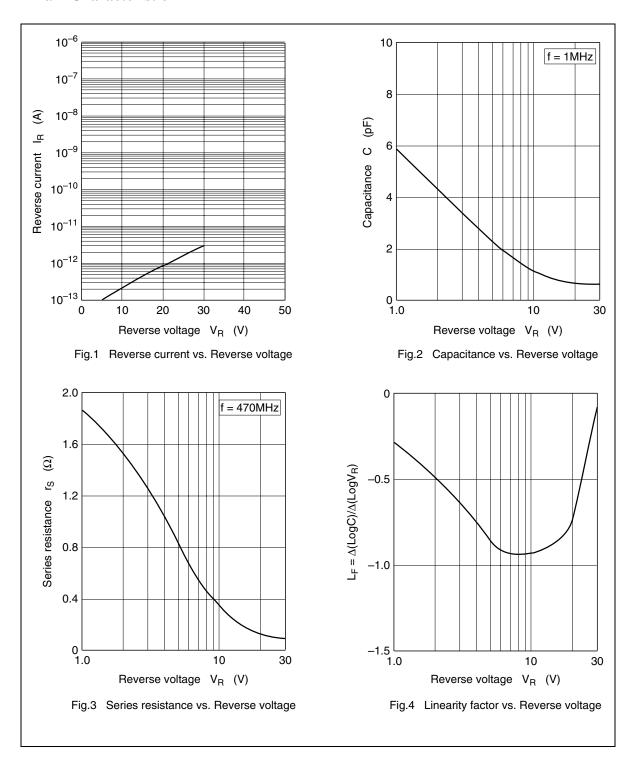
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 30 V
	I _{R2}	_	_	100		V _R = 30 V, Ta = 60°C
Capacitance	C ₁	5.16	_	7.22	pF	V _R = 1 V, f = 1 MHz
	C ₂₅	0.48	_	0.76		V _R = 25 V, f = 1 MHz
Capacitance ratio	n	9.0	_	_	_	C ₁ /C ₂₅
Series resistance	r _s	_	_	1.2	Ω	V _R = 5 V, f = 470 MHz
Matching error	ΔC/C *1	_	_	6.0	%	V _R = 1 to 25 V, f = 1 MHz

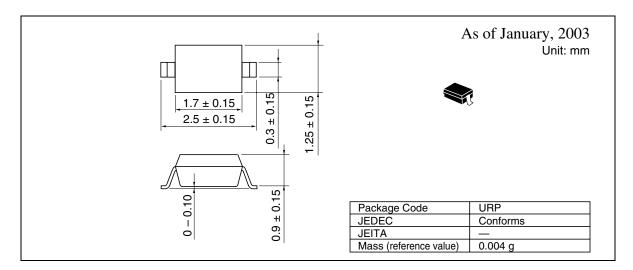
C.C system (Continuous Connected taping system) enable to make any 10 pcs of ΔC/C continuous in a reel, expect extention to another group.
 Calculate Matching Error,

$$\Delta C/C = \frac{(Cmax - Cmin)}{Cmin} \times 100 \text{ (\%)}$$

Main Characteristic



Package Dimensions



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